ABSTRACT

A semiconductor chip mounting component includes a support structure having a top surface, a bottom surface, and a gap extending through the support structure between the surfaces for defining first and second portions of the support structure. The component includes a plurality of electrically conductive leads, each lead having a connection section extending across the gap, the connection section having a first end disposed on the support structure on one side of the gap, a second end secured to the support structure on an opposite side of the gap and a frangible section. The mounting component includes at least one elongated bus disposed alongside the gap on one of the first and second portions of the support structure, wherein each of the leads extends across the gap and is connected to the bus, and wherein the leads are adapted to be bonded to contacts on a semiconductor chip by breaking the frangible sections of the leads so as to disconnect the leads from the bus.